

MILLIMETER WAVE POWER AMPLIFIERS STATE OF THE ART AND FUTURE TECHNOLOGY TRENDS

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CREATING THE NEXT[®]

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Asad Abiri, UCLA ADC Operations



Charles Sodini, MIT Sources of Innovation





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- Introduction
- State of the Art: Georgia Tech PA Survey (2000-present)
- Broadband Linear Efficient PAs
- Antenna-PA Co-Designs: Multi-Feed Mm-Wave Radiators
- Conclusion



• Need: large output power and peak efficiency



- Ensure sufficient link budget and compensate high path loss
- Drain Efficiency $\eta = P_{out}/P_{DC}$ and Power Added Efficiency $PAE = (P_{out}-P_{in})/P_{DC}$
- Thermal handling and device operation time



• Need: broad or reconfigurable carrier bands

Potential 5G mm-wave bands



• Multi-standard communication or frequency reconfigurability and agility

• **Need:** high back-off efficiency



PA Average Efficiency



- Spectrum-efficient modulation (high-order QAM, OFDM) leads to high PAPR
- System average efficiency largely depends on the back-off efficiency



• Need: high linearity



 Inherently linear for multi-Gbit/s complex modulations with minimum or even no digital pre-distortions (DPD)

Unreasonable Request for "Perfect" Mm-Wave PAs...





Unreasonable Request for "Perfect" Mm-Wave PAs...





...The reasonable man adapts himself to the world. The unreasonable one persists in trying to adapt the world to himself. Therefore all progress depends on the unreasonable man...

George Bernard Shaw (26 July 1856 – 2 November 1950),
 Nobel Prize Laureate for Literature in 1925.

Challenge 1: Gain, Stability, and Efficien



Challenge 2: Output Power and Efficiency

- Limited device output voltage swing $(V_{DD}-V_{knee})$ and power
- $P_{out} = i_{max} \times (V_{DD} V_{knee})/2$ = $(V_{DD} - V_{knee})^2/2R_L$
- Larger devices or more devices
- Lossy impedance transformation

• I. Aoki, S. Kee, D. Rutledge, and A. Hajimiri, *IEEE T-MTT*, 2002.

Typical Optimum Load Impedance and Peak PAE[†] vs. Device Sizes @28GHz +j1.0 +j0.5 +j2.0





Challenge 3: Efficiency and Linearity

GEMS 💮

Measured AM-AM/AM-PM vs. P_{out} backoff for a typical CMOS 28GHz 18dBm Class-AB PA



• Avoid amplitude clipping over $OP_{1dB} \rightarrow An$ extra power back-off of 2.8dB

• $P_{ave} = P_{sat} - 2.8 dB - 6 dB PAPR \rightarrow - 8.8 dB PBO \rightarrow -9\%$ average PAE



Measured AM-AM/AM-PM vs. P_{out} backoff for a typical CMOS 28GHz 18dBm Class-AB PA



Avoid AM-PM distortion → An additional power back-off of ~2dB

• $P_{ave} = P_{sat} - 2dB - 2.8dB - 6dB PAPR \rightarrow -10.8dB PBO \rightarrow -6\%$ average PAE

Challenge 4: Efficiency, Data Rate, Lineady







- Introduction
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- CW/Modulation Performance: Frequency (0.5-200GHz), Technologies, Pout, PAE, EVM, etc.
- Version-3 available to the public at http://gems.ece.gatech.edu/PA_survey.html



Saturated Output Power vs. Frequency (All Technologies)

State-of-the-Art PA P_{sat} vs. Frequency (CMOS and SiGe)



State-of-the-Art PA P_{sat} vs. Frequency (GaN and InP)



• P_{sat} vs. Frequency vs. Technologies



- P_{sat} vs. Frequency vs. Technologies
- Output power vs. frequency

OSCIIIators

Multipliers

-20

-30

0.1

- Power generation scheme vs. frequency
- Power amplifiers and Fundamental Oscillators (~200GHz)
- Multipliers and Harmonic Oscillators (~500GHz and above)



State-of-the-Art PA P_{sat} vs. Peak PAE (20-50GHz PAs)



• State-of-the-Art PA P_{sat} vs. Peak PAE (20-50GHz PAs)



EMS 😳

• 20-50GHz CMOS/SiGe PAs with 64QAM modulation test

PAs with MER<-20dB and >150MSym/s modulation rate. (Majority of the modulation signals have ~7dB PAPR. A few use OFDM 64QAM with ~9dB PAPR.)



• 20-50GHz CMOS/SiGe PAs with 64QAM modulation test HUGE DIFFERENCE between P_{out} / PAE in modulation tests vs. CW operations.



• 20-50GHz CMOS/SiGe PAs with 64QAM modulation test To push the boundary of average P_{out} and PAE requires linearization techniques,

power combining, and new architecture

Modulation and CW Performance Comparison for SiGe and CMOS (20-50GHz)







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Mm-Wave Linear Class-AB PAs in Silicon

- n GEMS 💮
- Balanced performance of efficiency, linearity, and modulation BW
- "RF-in-RF-out" PAs → System integration



A. Larie, *et al.*, *IEEE ISSCC 2015*.
60GHz Class AB/C in 28nm FD-SOI



- S. Shakib, et al., IEEE ISSCC 2017.
- 28GHz Class AB in 40nm CMOS



- A. Agah, et al., IEEE RFIC 2012.
- 45GHz Stacked Class AB in 45nm SOI



A. Sarkar, B. Floyd, *IEEE T-MTT 2017*.
D. Zhao, P. Reynaert, *IEEE JSSC 2013*.
28GHz Class AB in 130nm SiGe
60GHz Class AB in 40nm CMOS





- UC Berkeley & Intel
- S. Thyagarajan, A. Niknejad, C. D. Hull, *IEEE TCAS-I 2014*.
- 60GHz Class AB in 28nm CMOS 31

Power Amplifier Classes



- Linear-Mode PAs: Classes A, B, AB, and C
- Assume linear device, harmonic short termination, no triode



Power Amplifier Classes



Class	Conduction Angle	Bias Point	Efficiency (Max Theoretical)	Gain	Linearity	Output Power (Normalized)
A AB	360° 360°–180°	Higher than V ₇	50% 50—78.5%	Largest ↓ Lowest	Good ↓ Bad	1 Larger than 1 (max 1.15 at 240°)
B C	180° 180° – 0°	V _T Lower	78.5% 78.5–100%			1 1 at 180° 0 at 0°



Power Amplifier Linearity



AM-AM and AM-PM distortions



- In-band: Error Vector Magnitude (EVM)
- Out-of-band: Adjacent
 Channel Power Ratio (ACPR)

ACPR



• Dynamic AM-AM/AM-PM and memory effect

0

Multi-Gated Transistors PA



g_{m3} cancellation of PA stage

• Negative g_{m3} of M1 (Class-AB) is cancelled-out by the positive g_{m3} of M2-M4 (Class-C) \rightarrow Wide near-zero g_{m3} region, suppressing IMD3



Multi-Gated Transistors PA



- Average input capacitance of PA stage
 - Average input capacitance of M1 (Class-AB) \downarrow
 - Average input capacitance of M2-M4 (Class-C) ↑
- \rightarrow Less average input capacitance variance of common source transistors



D. Jung, H. Zhao, and H. Wang, IEEE IMS 2018 and T-MTT 2019.
PA AM-PM Distortion



• AM-PM distortion in complex modulation



- PA input device nonlinear capacitor
- PA input Miller capacitor and nonlinear g_m
- PA output device nonlinear capacitor
- M. Vigilante and P. Reynaert, JSSC 2018 and RFIC 2017
- J. Park, Y. Wang, S. Pellerano, C. Hull, H Wang, ISSCC 2017 and JSSC 2018
- S. Golara, S. Moloudi, and A. A. Abidi, TCAS-I 2017

PA AM-PM Distortion



2164

2164

2523

dB

dB

sym



EVM

Mag Err

= 5.5316

= 4.6047

Phase Err = 2.4050

Freg Err = -826.76

IQ Offset = -47.325

Quad Err = -113.39

%rms

%rms

deg

Hz

dB

mdeg

17.174

-16.528

-13.851

% pk at sym

% pk

SNR (MER) = 25,143

Gain Imb = 0.086

deg pk at sym

- PMOS varactor cancellation
- Wideband matching network
- PA-Driver AM-PM cancellation
 - M. Vigilante and P. Reynaert, JSSC 2018 and RFIC 2017

Mm-Wave Switching PAs or Harmonically-Tuned PAs in Silicon



Superior efficiency and output power



- K. Datta, H. Hashemi, IEEE JSSC 2014.
- 130nm SiGe (BV_{CEO}=1.7V, BV_{CBO}=5.9V)
- 2-Stack Class-E @ 41GHz: P_{sat} 23.4dBm, Peak PAE 31-34.9%.

- A. Chakrabarti and H. Krishnaswamy, *IEEE JSSC 2014*.
- 45nm CMOS SOI (nominal V_{DD}=~1V)
- 2-Stack Class-E @ 47GHz: P_{sat} 17.6dBm, Peak PAE 34.6%.







- S. Mortazavi, K.-J. Koh, IEEE JSSC 2016.
- 130nm SiGe (BV_{CEO} =1.7V, BV_{CBO} =5.9V)
- Class-F⁻¹ @ 24GHz: P_{sat} 18dBm, Peak PAE 50%.

A Continuous-Mode F⁻¹-like Harmonic Tuning Broadband PA in SiGe



- High modulation efficiency over a large carrier BW
- Ultra-compact





Input



- Global Foundries 0.13µm SiGe
- Core area: 0.29mm²

Exploring and enhancing transformer parasitics



• T. Li, M. Huang, and H. Wang, IEEE ISSCC 2018 and IEEE T-MTT 2019. $_{\rm 40}$

A Continuous-Mode F⁻¹-like Harmonic Tuning Broadband PA in SiGe





• T. Li, M. Huang, and H. Wang, IEEE ISSCC 2018 and IEEE T-MTT 2019.

A Continuous-Mode F⁻¹-like Harmonic Tuning Broadband PA in SiGe



64-QAM modulation at 28.5GHz (EVM < -25dB up-to 18Gb/s)



• 256-QAM modulation at 28.5GHz (EVM < -30.5dB up-to 8Gb/s)

A: Ch1 256QAM Meas Time 👻	A: Ch1 256QAM Meas Time 🔹	A: Ch1 256QAM Meas Time 👻
-31.3dB EVM -31.3dB EVM 27dB MER 8.8dBm Pavg -1.5	Ins EQ 1.5 -30.5dB EVM 26.2dB MER 26.2dB MER 8.8dBm Pavg 20.4% PAE _{PA}	Ins EO 1.5 -30.5dB EVM 26.2dB MER 26.2dB MER 300 8.7dBm Pavg -1.5 -1.5
-3.507936508 0.5GSym/s, 4Gb/s 3.5079365079	-3.5079365079 0.8GSym/s, 6.4Gb/s 3.50793650794	-3.5079365079 1GSym/s, 8Gb/s 3.50793650794
EVAM = 2.7221 % mms 8.4487 % pk at syme 833 Mag Err = 1.0068 % mms 8.4376 % pk at syme 833 Phase Err = 2.6518 MHz No Office = -53.067 dB 8.4487 dbg pk at syme 552 Froq Err = 2.6518 MHz Qued Err = -261.45 mdeg Gein kmb = -0.018 dB	EVAI = 2,9928 % mas Mag Ev = 2,1157 % mas Fhate Ev = 3,0942 dog -24,278 dog pit at tyrn 54 Fhate Ev = 3,0942 dog -24,278 dog pit at tyrn 285 Freq Ev = 28,394 kHz ROOKet = -42,84 dB Quad Ev = -73,840 maleg Soin Mab = 0,007 dB	EVN4 = 3.0120 %mms 6.4357 % pk at epm 802 Mag Err = 2.0316 %mms -5.6138 % pk at epm 48 Phose Err = 3.0363 deg 43.767 deg pk at epm 901 Frag Err = 3.3663 deg Frag Err = -71.533 mdeg Com imb = -0.016 d8

• T. Li, M. Huang, and H. Wang, IEEE ISSCC 2018 and IEEE T-MTT 2019.

A Continuous-Mode Class F/F⁻¹-like Harmonic Tuning Broadband PA in 45nm CMOS SOI

- Small-signal CW
- 20 55 20 • Ŝ₂₂ BW_{1dB}=54.3% (23.5-41GHz) 50 S₂₁=12,3dB@31GHz 18 45 10 16 **BW**_{3dB}=51% 40 S-parameter (dB) . 35[⊗] (25.9-43.7GHz) P_{sat} (dBm) PAEpeak=46% 14 0 ⁻³⁰ AE 12 Class-F Class-I -10 25 mode 10 20 - PAE -20 15 24 26 28 32 34 36 38 40 25 30 42 20 30 35 40 45 50 Frequency (GHz) Frequency (GHz) BW_{3dB}=25.9-43.7GHz (51%) P_{sat} 1dB BW=23.5-41GHz (54.3%)
 - BW_{S11}=27.3-43.2GHz (45.1%)

Class F/F⁻¹ Mode Transition at 35GHz

Large-signal CW

• T. Li and H. Wang, IEEE RFIC 2018 and IEEE T-MTT 2019.

Mm-Wave Doherty PAs or Doherty-Like PAs in Silicon



- \checkmark Large modulation bandwidth \rightarrow Broadband 5G
- \checkmark RF-in-RF-out operation \rightarrow Drop-in solution
- X On-chip output passive network
- X Cooperation between two PA paths
- X Carrier bandwidth



- B. Kim, J. Kim, I. Kim, J. Cha, IEEE microwave magazine, 2006.
- S. Hu, S. Kousai, and H. Wang, IEEE T-MTT 2015.

Example Mm-Wave Doherty PAs or Doherty-Like PAs in Silicon





- A. Agah, et al., IEEE JSSC 2013.
- 45GHz Doherty PA in 45nm FD-SOI
- Active phase-shift for auxiliary path
- Stacked transistor PA core



- E. Kaymaksut, D. Zhao, P. Reynaert, *IEEE T-MTT 2015*.
- 72GHz Doherty PA in 40nm CMOS
- XFMR series Doherty combiner



- M. Özen, et al., IEEE MWCL 2017.
- 20GHz Doherty PA in 130nm SiGe
- Low loss Doherty power combiner



- N. Rostomyan, et al., IEEE MWCL 2018.
- 28GHz Doherty PA in 45nm CMOS SOI
- Low loss Doherty power combiner



- C. Chappidi, X. Wu, K. Sengupta, *IEEE JSSC 2018*.
- 30-50GHz Doherty-like PA in 130nm SiGe
- RF power DAC
- Multi-port network



Broadband and low-loss Doherty parallel combiner



Conventional design

Impedance transformation ratio of TL₁ at 6dB power back-off: 4

$$Z_{01} = R_{opt}, \ Z_{02} = \sqrt{R_L R_{opt}/2}$$
 * R_{opt}=41.3Ω

Introduced design

Impedance transformation ratio of TL₁ at 6dB power back-off: 1.65

$$Z_{01} = Z_{02} = \sqrt{2R_LR_{opt}}, \ Z_{03} = 2R_L$$

Enhanced passive efficiency in power back-off

Enlarged bandwidth

X Passive area

• A. Grebennikov, et al., IEEE T-MTT 2012.



• Introduced design – Broadband/Iow-Ioss Doherty parallel combiner

✓ Compact

- ✓ Desired Doherty load modulation
- Enhanced passive efficiency in power back-off
- Extended bandwidth



- GEMS 💮
- Introduced design Broadband/low-loss Doherty parallel combiner

Compact

- Desired Doherty load modulation
- ✓ Enhanced passive efficiency in power back-off
- Extended bandwidth





World-first 28/37/39GHz multiband Doherty PA for 5G MIMO



Global Foundries
 130nm SiGe BiCMOS



- CW measurements Small-signal and large-signal
 - Reconfigurable operation covers three 5G bands of 28/37/39GHz.





- CW measurements Power back-off at 37GHz
 - +17.1dBm P_{sat}, +15.5dBm P_{1dB}, 27.6% peak CE
 - 1.92× efficiency enhancement over class-B at 6dB PBO
 - 500MSym/s 64QAM (3Gb/s) without digital predistortion (DPD)



Pushing the Doherty PA Further



Doherty / Doherty-like PA

- PBO efficiency enhancement, wideband mod. BW
- Cooperation between Main and Aux PA path

Polar Digital PA/TX (Power DAC)

- •• Precise control and reconfiguration
- AM-/PM-path bandwidth expansions
- Out-of-band (OOB) images and in-band noise
- Limited ENOB for mm-wave digital PA



[S. Hu, H. Wang, et al., IEEE TMTT, vol. 63, no. 2, pp. 580-597, Feb. 2015.]

New Doherty PA/TX Architecture?



• Conceptual Schematic for Mixed-Signal Doherty PA

(1) Main path: analog PA Aux path: array of binary-weighted PA cells
(2) Input signal: generic complex modulated signal (NOT constant envelop signal)





• Small input envelopes: Analog Regime

Only Main path analog PA is turned on \rightarrow Operating as an analog PA





• Large input envelopes: Mixed-Signal Regime

 \rightarrow Aux sub-PAs are dynamically turned on.





Small Input Envelopes: Analog Regime

A large dynamic range with no quantization error or LSB limitation, unlike digital PA





• Large Input Envelopes: Mixed-Signal Regime

The output envelope is interpolated by both envelope-varying input and real-time Aux PA digital controls. \rightarrow Largely suppressing quantization errors





• Mixed-Signal Doherty PA (3-bit) Gain, Phase, and Efficiency





• Quantization Errors: Mixed-Signal Doherty PA vs. Digital PA (3-bits)



Signal Interpolation and Sampling Images





Close-in spectrum and sampling images: Mixed-signal Doherty PA (3-bit) vs. Digital PA (3-bit)





• "Super Resolution": With the same number of bits, mixed-signal Doherty PA achieves superior linearity than conventional digital PA.



Why Super Resolution?

(1) Small input envelopes: An analog PA with large dynamic range and no quantization error.
(2) Large input envelopes: Output envelopes by both envelope-varying input and real-time Aux PA digital controls. Quasi "First-Order Hold (FOH)" → Much smaller quantization errors and sampling images

(3) Non-uniform quantization

Prototype Implementation

• 28GHz Mixed-Signal Doherty PA with only 3bit Aux controls (ISSCC2019, ISSCC2017, JSSC2019)

Cascoded PA stage (476 μ m/40nm) and V_{DD} = 2.0 V CS driver stage (153.2 μ m/40nm) and V_{DD} = 1.0 V











• Small-Signal CW Measurement





• Large-Signal CW Measurements at 28GHz





Modulation measurement setup







Modulation Measurements: EVM and ACPR

2.0GSym/s (12Gb/s) 64-QAM without predistortion



First demonstration of 64-QAM modulation with only 3-bit digital controls P_{avg}=15.6dBm PAE_{avg}=27.8% $P_{DC,digital} = 9mW$ rms EVM=-24.4dB EVM = 6.00 %rms Mag Err = 3.92 %rms Phase Err = 3.38 deg MER = 24.4 dB



Modulation Measurements: Out-of-Band Spurs and Delay Mismatch Effects







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- State of the Art: Georgia Tech PA Survey (2000-present)
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Can we synergistically merge antennas/EMs together with active circuits?

- Novel hybrid antenna-electronics with "On-Radiator" functions
 - (1) Power Combining/Splitting
 - (2) Impedance Scaling and Filtering
 - (3) Active Load Modulation
 - (4) Reconfigurability



- R. King and T. Wu, "The Cylindrical Antenna with Arbitrary Driving Point," IEEE T-AP, Sept. 1965.
- S. Bowers, A. Hajimiri, "Multi-Port Driven Radiators," IEEE T-MTT, Dec. 2013.
- H. Wang, T. Chi, H. Nguyen, S. Li, J. Park, *et al., IEEE APS/URSI 2016, T-AP 2017, ISSCC 2017, ISSCC 2018, RFIC 2018.*

Multi-Feed Radiator for Direct On-Antenna Power Combining



Conventional power combining technique I

Passive on-chip/on-package combining networks



 Lossy passive combiner degrades efficiency, especially with large number of power devices and high impedance-transformation ratio

Dual-Feed Mm-Wave Doherty Radiator




Multi-Feed Radiator for Direct On-Antenna Power Combining

Conventional power combining technique II
 Spatial power combining by large-scale antenna arrays



- \checkmark Ideally lossless and 20logN EIRP enhancement
- ➤ Large antenna panel size
- ➤ Narrow antenna beamwidth → complicates Tx/Rx alignment for dynamic and mobile applications



Multi-Feed Radiator for Direct On-Antenna Power Combining

• Multifeed antenna (MFA) driven by multiple power amplifiers





-60

Single-Element 0.5λ Dipole Half-Power Beamwidth = 78°

0 0dE

-10dB

-20ďB

- ✓ Power combining direct on antenna → boost output power
- ✓ Simplify impedance transformation \rightarrow increase efficiency
- ✓ Single antenna footprint \rightarrow maintain field of view
- ✓ Employed in an array \rightarrow further increase EIRP or beam-steering
- T. Chi et al., AP-S 2016, T-AP 2017, ISSCC 2017, IMS 2018]

60

90

60GHz On-Chip Linear Radiator



 Linear radiator (antenna + 16 PAs) at 60GHz in 45nm CMOS SOI

"On-Antenna" Close-to-Ideal Parallel Combiner



• T. Chi et al., ISSCC, Feb. 2017.

60GHz On-Chip Linear Radiator





Direct On-Antenna Power Combining



A 69-79GHz CMOS multi-port radiator with +35.7dBm CW EIRP



• B. Abiri, A. Hajimiri, IEEE ISSCC 2018.





Multi-Feed Radiator for Direct On-Antenna Active Load Modulation

 Advanced "on-antenna" active load modulation transmitters?
 TX system back-off efficiency



• Doherty Linear TX Architecture Main $PA \angle 0^{\circ}$ RF_{in} N/4 T-Line $Aux PA \angle -90^{\circ}$ Z_{Load}

- B. Kim, et al., *IEEE Microwave Magazine*, Oct. 2006.
- S. Hu and H. Wang, *IEEE ISSCC*, 2017.

Outphasing Nonlinear TX Architecture



Hongtao Xu, et al., *IEEE J. Solid-State Circuits*, May 2011.
T. Barton, et al., *IEEE T-MTT*, Apr. 2016.
78

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60GHz Doherty Radiator

CW measurement

• At 63GHz, +18.8 dBm P_{1dB}, 24% PAE _{0dB} PBO and 18.3% PAE 6dB PBO • 1.52 × PAE enhancement over class-B at 6dB PBO

- Carrier Frequency = 63GHz ----- P1dB 35 – – Peak PAE ⊃sat (dB), P1dB (dB), Peak PAE (%) Main PA Main + Aux PAE Enhancement Ratio at 6dB PBO PG 30 2 PG(dB), DE_PA(%),PAE(%) 30 onlv PA ---- PAE 25 25 -DE PA 1.8 20 1.52 × 20 15 over class B 1.6 10 15 6dB PBO 3.04 × 5 over class A 45 P1dB 1.4 10 0 61 62 63 68 69 64 65 66 67 16 18 2 6 8 20 Δ 10 12 14 Frequency (GHz) Pout (dBm)
- H. T. Nguyen, T. Chi, S. Li, H. Wang, IEEE ISSCC 2018 and IEEE JSSC 2018.

 1.45-1.53 × PAE enhancement over class-B at 6dB PBO







Modulation measurement

The Doherty radiator combines the power on the antenna before radiation

 \rightarrow Maintaining constellation over the *entire antenna* FoV

Undistorted modulation (in both E-plane and H-plane) over full FoV



• H. T. Nguyen, T. Chi, S. Li, H. Wang, IEEE ISSCC 2018 and IEEE JSSC 2018.

Multi-Antenna Coupling for N-Way Mm-Wave High-Order Doherty Radiator



• Realizing general N-Way Doherty TX on radiator



• H. T. Nguyen and H. Wang, *IEEE ISSCC 2019.*

Multi-Antenna Coupling for N-Way Mm-Wave High-Order Doherty Radiator



Measurements



• H. T. Nguyen and H. Wang, *IEEE ISSCC 2019.*

Multi-Feed Antenna for Nonlinear Chireix Outphasing Mm-Wave Transmitter



• Realizing high-efficiency Chireix Outphasing TX on radiator





64-QAM 1Gsym/s and 2.5Gsym/s



• S. Li, T. Chi, T. Huang, H. Nguyen, and H. Wang, *IEEE RFIC* 2018 and JSSC 2019. — *RFIC Best Student Paper Award*

World-First Mm-Wave Polarization-Duplex TRX + Chip-to-Chip Demonstration



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- Globalfoundries 45nm CMOS SOI
- No digital pre-distortion (DPD), channel equalization, or digital cancellation



• T. Chi, J. Park, S. Li, and H. Wang, ISSCC 2018, JSSC 2018



Outline



- Introduction
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Conclusion and Future Directions



- Trade-offs of Carrier Bandwidth, Efficiency, Linearity, and Modulation Rate
- Future Directions
 - Architecture:
 - Broadband, linear, and efficient PA architectures
 - > Antenna-PA/TX/RX co-designs
 - Compound semiconductor PA and heterogeneous integration
 - **Reliability:** Silicon PA in MIMO arrays
 - Linearization: Low overhead Gbit/s DPD



- DARPA, NSF, DoD, and Industry Sponsors
- Global Foundries for chip fabrication
- Members of Georgia Tech GEMS Lab

Thank you!





Thank you!